

1. Description

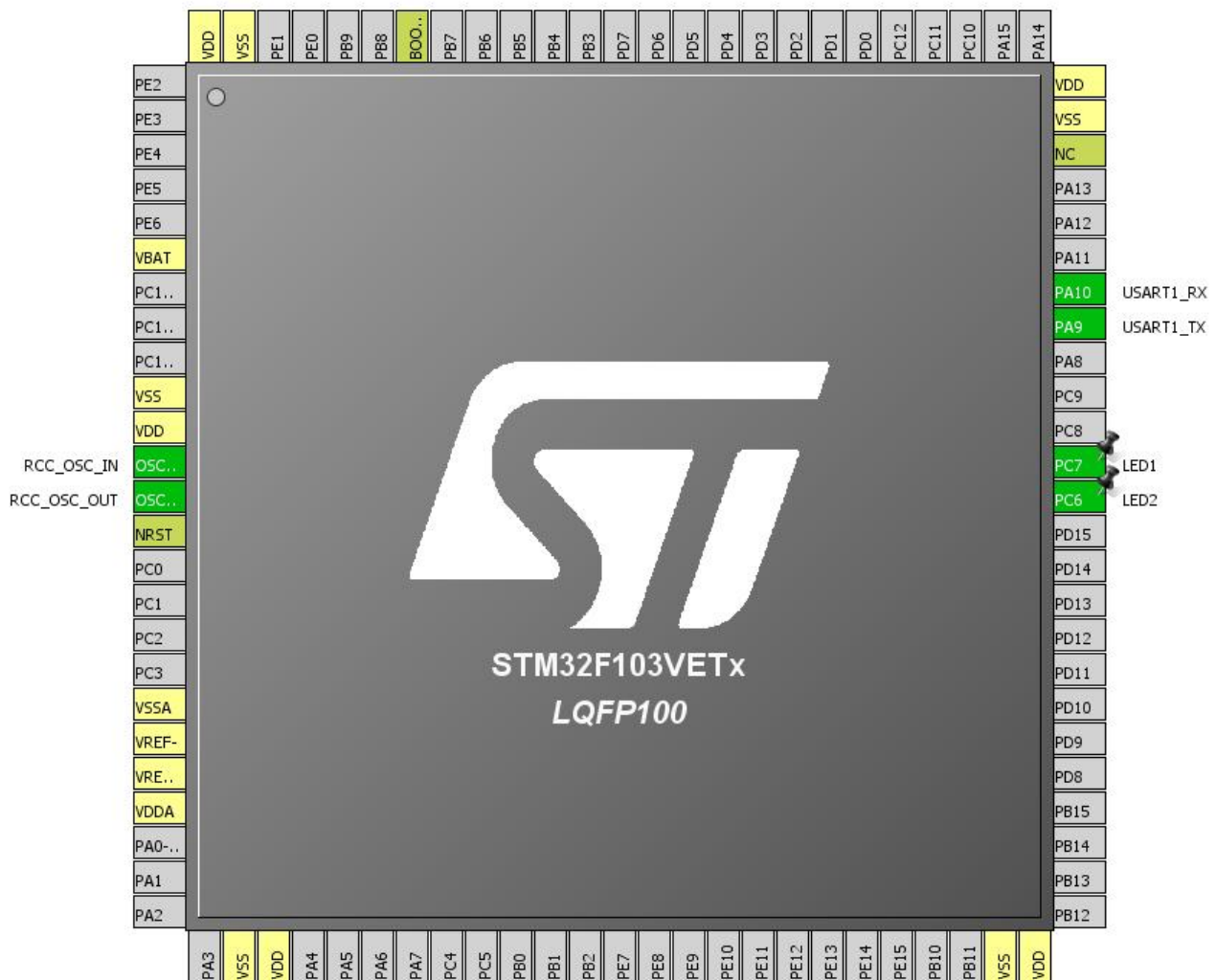
1.1. Project

Project Name	internal_temperature_sensor
Board Name	custom
Generated with:	STM32CubeMX 4.26.0
Date	08/10/2018

1.2. MCU

MCU Series	STM32F1
MCU Line	STM32F103
MCU name	STM32F103VETx
MCU Package	LQFP100
MCU Pin number	100

2. Pinout Configuration



3. Pins Configuration

Pin Number LQFP100	Pin Name (function after reset)	Pin Type	Alternate Function(s)	Label
6	VBAT	Power		
10	VSS	Power		
11	VDD	Power		
12	OSC_IN	I/O	RCC_OSC_IN	
13	OSC_OUT	I/O	RCC_OSC_OUT	
14	NRST	Reset		
19	VSSA	Power		
20	VREF-	Power		
21	VREF+	Power		
22	VDDA	Power		
27	VSS	Power		
28	VDD	Power		
49	VSS	Power		
50	VDD	Power		
63	PC6 *	I/O	GPIO_Output	LED2
64	PC7 *	I/O	GPIO_Output	LED1
68	PA9	I/O	USART1_TX	
69	PA10	I/O	USART1_RX	
73	NC	NC		
74	VSS	Power		
75	VDD	Power		
94	BOOT0	Boot		
99	VSS	Power		
100	VDD	Power		

* The pin is affected with an I/O function

5. IPs and Middleware Configuration

5.1. ADC1

mode: Temperature Sensor Channel

5.1.1. Parameter Settings:

ADCs_Common_Settings:

Mode Independent mode

ADC_Settings:

Data Alignment Right alignment

Scan Conversion Mode Disabled

Continuous Conversion Mode **Enabled ***

Discontinuous Conversion Mode Disabled

ADC_Regular_ConversionMode:

Enable Regular Conversions Enable

Number Of Conversion 1

External Trigger Conversion Source Regular Conversion launched by software

Rank 1

Channel Channel Temperature Sensor

Sampling Time 1.5 Cycles

ADC_Injected_ConversionMode:

Number Of Conversions 0

WatchDog:

Enable Analog WatchDog Mode false

5.2. RCC

High Speed Clock (HSE): Crystal/Ceramic Resonator

5.2.1. Parameter Settings:

System Parameters:

VDD voltage (V) 3.3

Prefetch Buffer Enabled

Flash Latency(WS) 2 WS (3 CPU cycle)

RCC Parameters:

HSI Calibration Value 16

HSE Startup Timeout Value (ms) 100

LSE Startup Timeout Value (ms) 5000

5.3. SYS

Debug: No Debug

Timebase Source: SysTick

5.4. USART1

Mode: Asynchronous

5.4.1. Parameter Settings:

Basic Parameters:

Baud Rate	115200
Word Length	8 Bits (including Parity)
Parity	None
Stop Bits	1

Advanced Parameters:

Data Direction	Receive and Transmit
Over Sampling	16 Samples

* User modified value

6. System Configuration

6.1. GPIO configuration

IP	Pin	Signal	GPIO mode	GPIO pull/up pull down	Max Speed	User Label
RCC	OSC_IN	RCC_OSC_IN	n/a	n/a	n/a	
	OSC_OUT	RCC_OSC_OUT	n/a	n/a	n/a	
USART1	PA9	USART1_TX	Alternate Function Push Pull	n/a	High *	
	PA10	USART1_RX	Input mode	No pull-up and no pull-down	n/a	
GPIO	PC6	GPIO_Output	Output Push Pull	No pull-up and no pull-down	Low	LED2
	PC7	GPIO_Output	Output Push Pull	No pull-up and no pull-down	Low	LED1

6.2. DMA configuration

nothing configured in DMA service

6.3. NVIC configuration

Interrupt Table	Enable	Preenmption Priority	SubPriority
Non maskable interrupt	true	0	0
Hard fault interrupt	true	0	0
Memory management fault	true	0	0
Prefetch fault, memory access fault	true	0	0
Undefined instruction or illegal state	true	0	0
System service call via SWI instruction	true	0	0
Debug monitor	true	0	0
Pendable request for system service	true	0	0
System tick timer	true	0	0
PVD interrupt through EXTI line 16	unused		
Flash global interrupt	unused		
RCC global interrupt	unused		
ADC1 and ADC2 global interrupts	unused		
USART1 global interrupt	unused		

* User modified value

7. Power Consumption Calculator report

7.1. Microcontroller Selection

Series	STM32F1
Line	STM32F103
MCU	STM32F103VETx
Datasheet	14611_Rev12

7.2. Parameter Selection

Temperature	25
Vdd	3.3

8. Software Project

8.1. Project Settings

Name	Value
Project Name	internal_temperature_sensor
Project Folder	D:\[project]\stm32f103vet6\github\internal_temperature_sensor
Toolchain / IDE	MDK-ARM V5
Firmware Package Name and Version	STM32Cube FW_F1 V1.6.1

8.2. Code Generation Settings

Name	Value
STM32Cube Firmware Library Package	Copy only the necessary library files
Generate peripheral initialization as a pair of '.c/.h' files	Yes
Backup previously generated files when re-generating	No
Delete previously generated files when not re-generated	Yes
Set all free pins as analog (to optimize the power consumption)	No

9. Software Pack Report